

Please amend the present application as follows:

Specification

The following is a copy of Applicant's specification that identifies language being added with underlining ("___") and language being deleted with strikethrough ("—") or double brackets ("[[]]"), as is applicable:

Page 4, line 21 through page 5, line 8.

Irrespective of whether the heat sink 102 is unitary or comprises separate top and bottom plates 104 and 106, the heat sink comprises a top surface 108 and a bottom surface 110. As indicated in FIGS. 1-3, extending from the top surface 108 of the heat sink 102 are one or more hollow prongs 112 that, for example, are configured as cylindrical tubes. One or more of the prongs 112, and typically each prong, includes an internal passage 114 through which fluid, such as air, may flow to remove heat that is transmitted from the processor P to the heat sink 102 and into the prongs. The size and number of the prongs 112 may be selected to suit the particular application in which the heat dissipation apparatus 100 is used. By way of example, however, the prongs 112 may be about 1-2 inches tall ~~an~~ and may number from about 10-30 (18 prongs are shown in the embodiment of FIGS. 1-5).

Page 7, line 22 through page 8, line 15.

In the embodiment described above in relation to FIGS. 1-6, the heat dissipation apparatus 100 includes its own integral internal and external flow fan modules. In other embodiments, however, the heat dissipation apparatus need not include such integral fan

modules. Instead, the internal and external airflows can be generated by one or more separate fans and simply delivered to the heat dissipation apparatus. In such a case, a single fan or fan module can be used to provide airflow to two or more heat dissipation apparatuses. Such an arrangement is illustrated in FIG. 7. As shown in that figure, two heat dissipation apparatuses 700 are provided in a computer C (*i.e.* within the computer box).[[.]] The heat dissipation apparatuses 700 are similar in construction to the heat dissipation apparatus 100 shown in FIGS. 1-6, but do not include integral fan modules. Instead, the heat dissipation apparatuses 700 are provided with airflow by a separate fan 702 of the computer C that is draws air into the computer through an inlet I of the computer box. As indicated in FIG. 7, an airflow director apparatus 704, which may include one or more conduits 706, is used to divide the airflow generated by the fan 702 into the internal and external airflows provided to the heat dissipation apparatuses 700. With such an arrangement, the size and/or weight of the apparatus used to dissipate heat from multiple processors may be reduced in that the number of fans used is reduced.